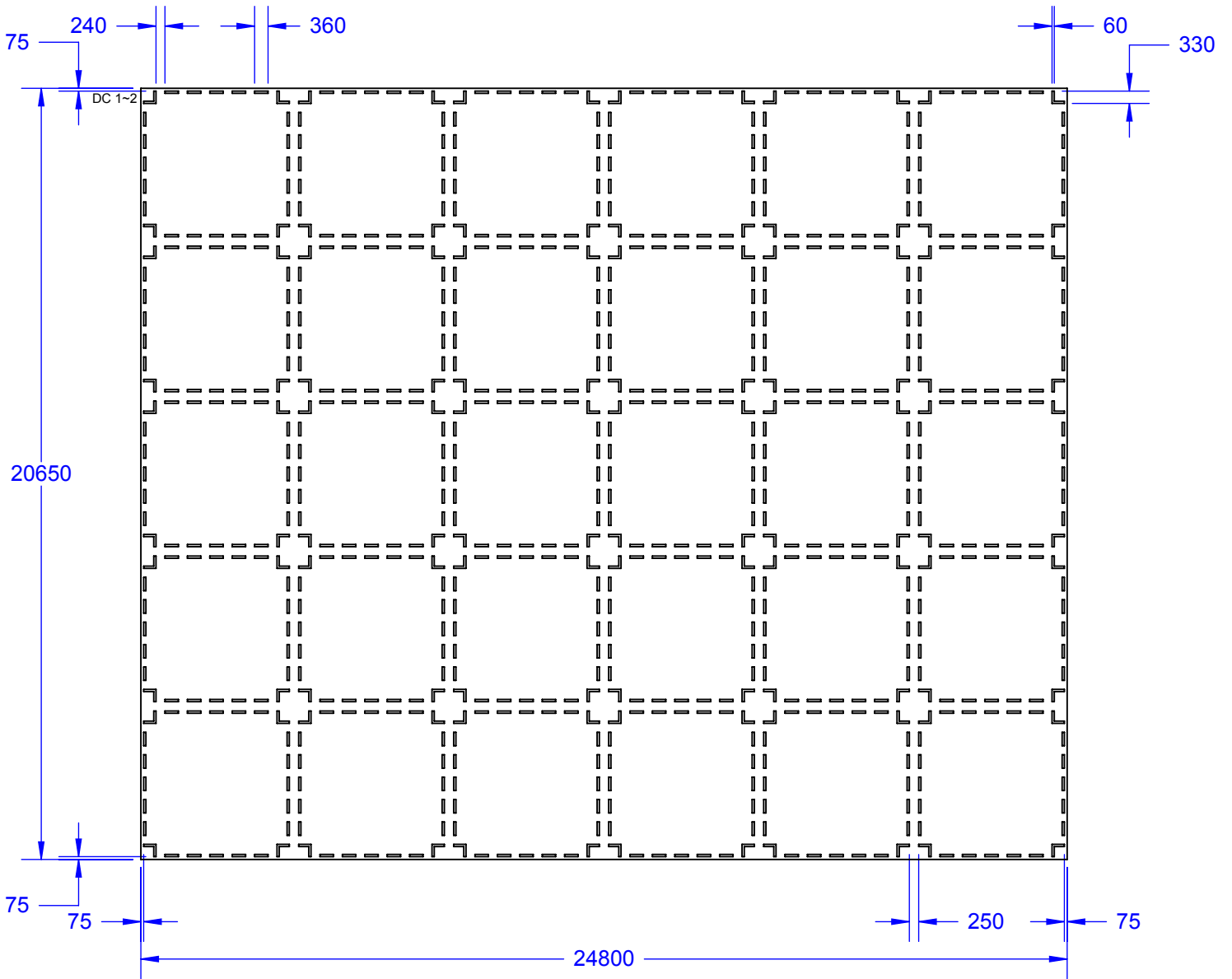


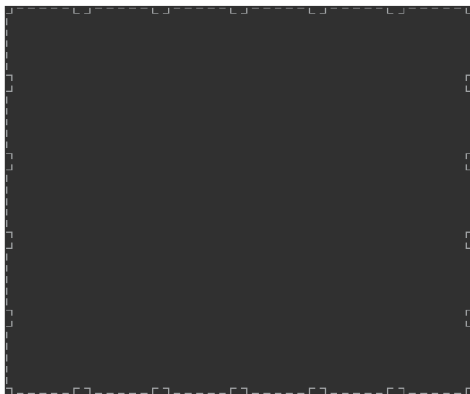
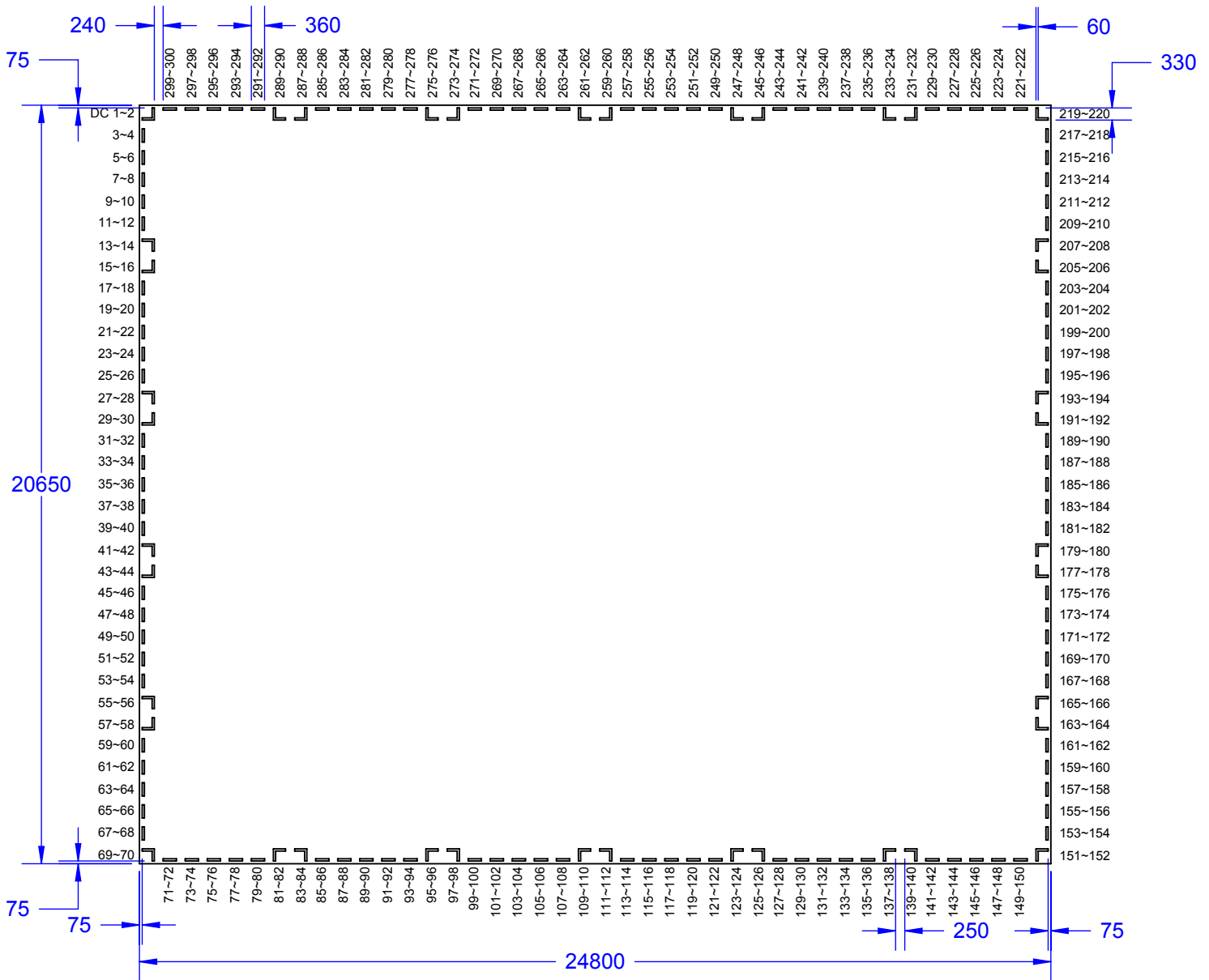
DAISY CHAIN TEST DIE WIRE BONDABLE SHOWN WITH CENTER PADS



- Notes: (Unless Otherwise Specified)
1. DIE MATERIAL IS SILICON.
 2. DIE THICKNESS 250 μ m ~ 725 μ m.
 3. METALLIZATION 1.0 μ m ALUMINUM (Al).
 4. DIE IS WITHOUT PASSIVATION.
 5. WIRE BONDABLE WITH GOLD (Au) WIRE.
 6. DAISY CHAIN PAIRS.

APPROVALS	DATE	TopLine [®]			
DRAWN T. Au	04/15/14				
ENG M. Hart	04/15/14	TITLE DAISY CHAIN TEST DIE TD150 21 x 25MM			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		6:1	A	154150	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

PERIMETER PAD TEST DIE DAISY CHAIN SHOWN WITHOUT CENTER PADS FOR CLARITY



SCALE 2.5:1

DIMENSION IN MICRONS
1.0mm = 1000µm

- Notes: (Unless Otherwise Specified)
1. DIE MATERIAL IS SILICON.
 2. DIE THICKNESS 250µm ~ 725µm.
 3. METALLIZATION 1.0µm ALUMINUM (Al).
 4. DIE IS WITHOUT PASSIVATION.
 5. WIRE BONDABLE WITH GOLD (Au) WIRE.
 6. DAISY CHAIN PAIRS.

APPROVALS	DATE	TopLine®			
DRAWN T.Au	04/15/14				
ENG M. Hart	04/15/14	TITLE DAISY CHAIN TEST DIE TD150 21 x 25MM			
MFG		SCALE 6:1	SIZE A	DRAWING NO. 154150	REV A
QA					
CUST		DO NOT SCALE DRAWING			SHEET 2 OF 2
REVISED					